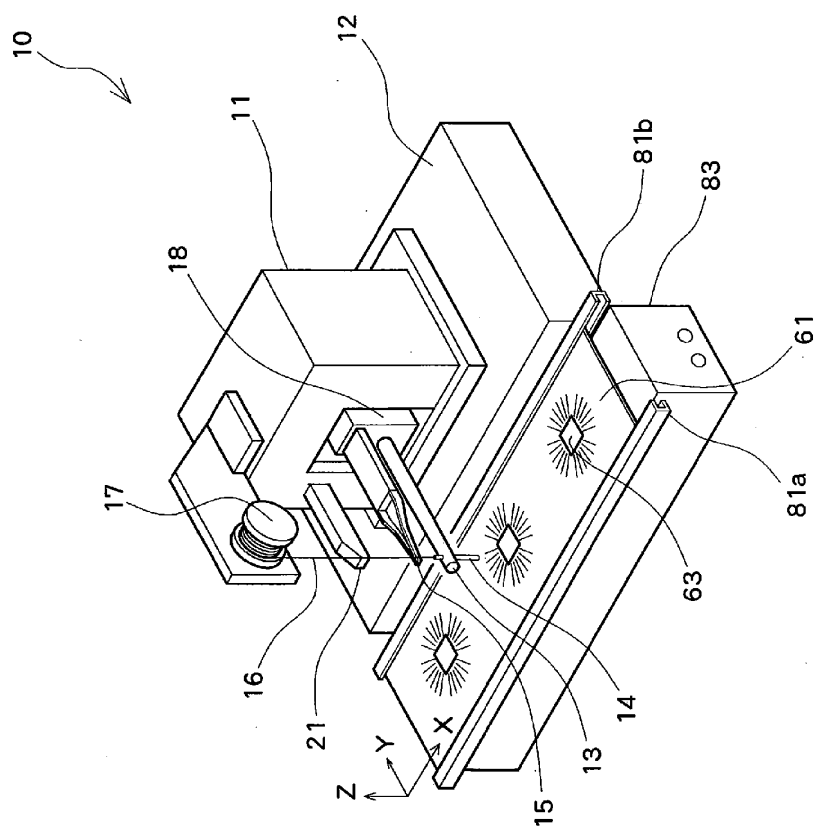
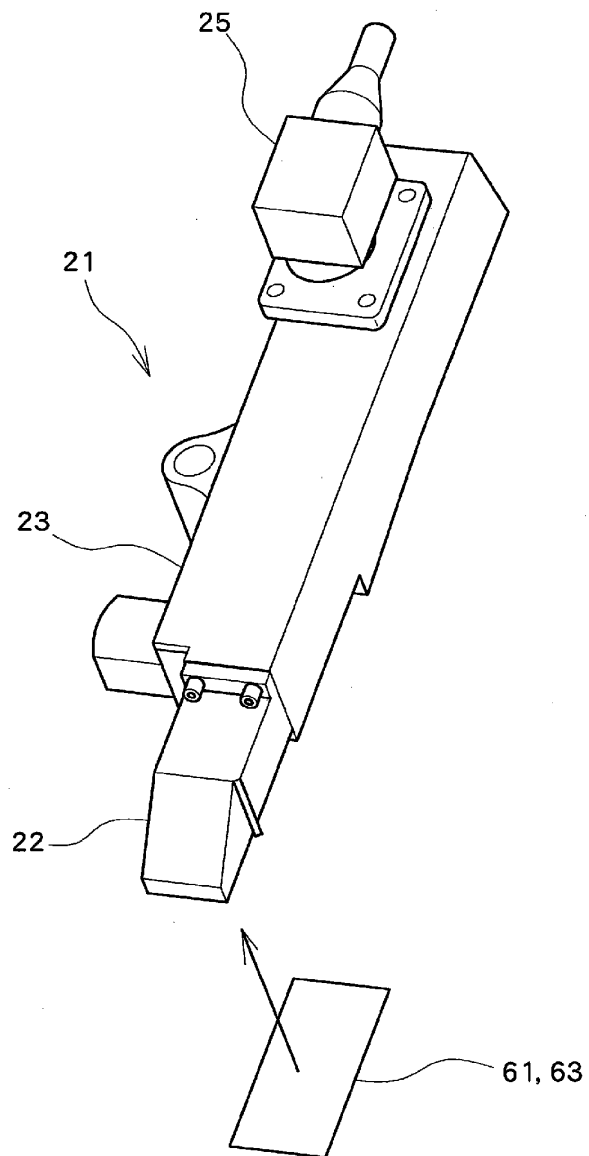


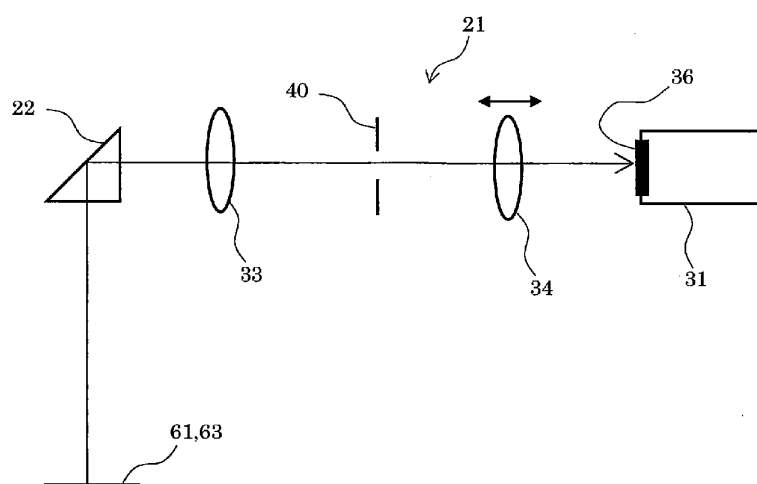
[図1]



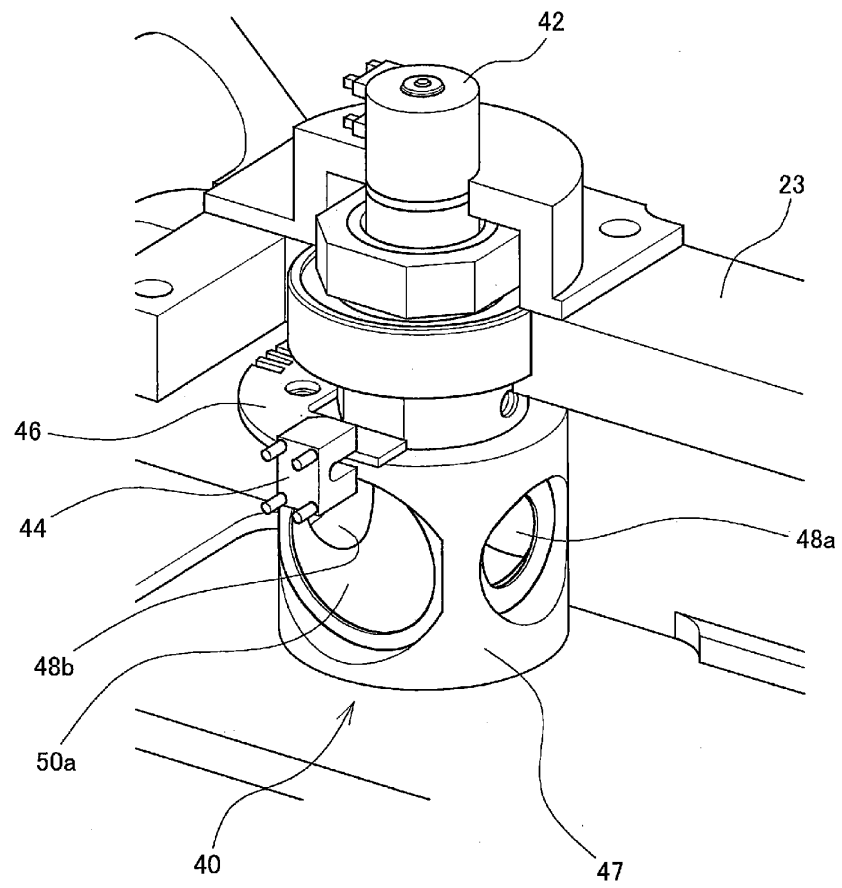
[図2]



[図3]



[図4]



【図5】

絞り穴径（NA）	光学分解能	被写界深度	行う処理
小さい ＜通常絞り＞	低い	深い	実装処理 （積層デバイスの実装処理など）
大きい ＜高分解能絞り＞	高い	浅い	付帯処理 （調整処理、測定処理など）

[図6]

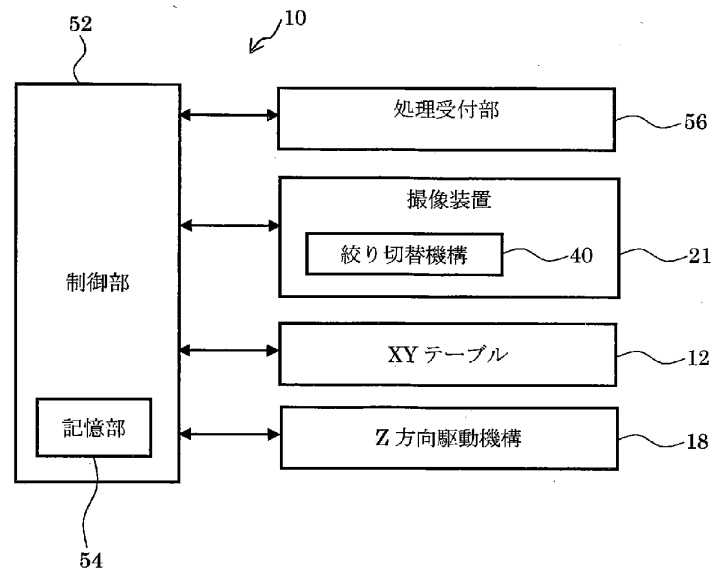
(A)



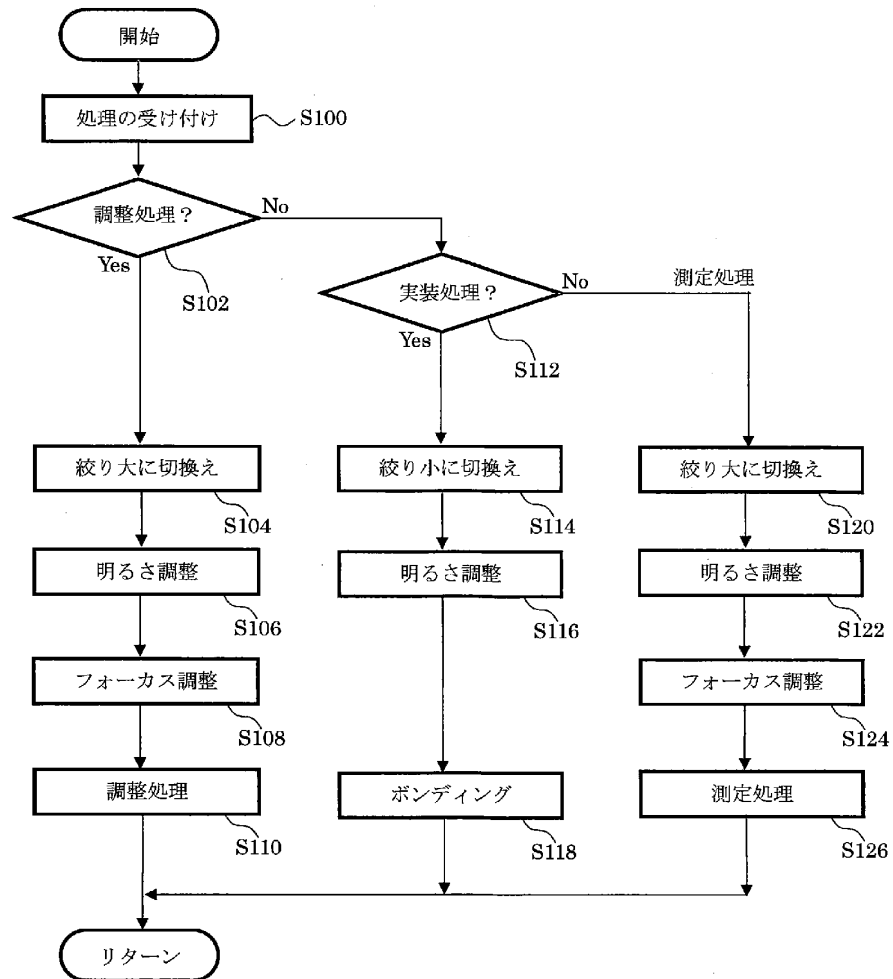
(B)



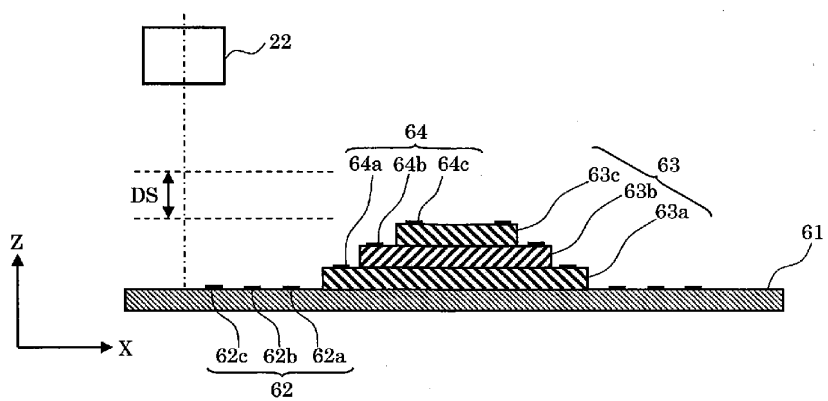
[図7]



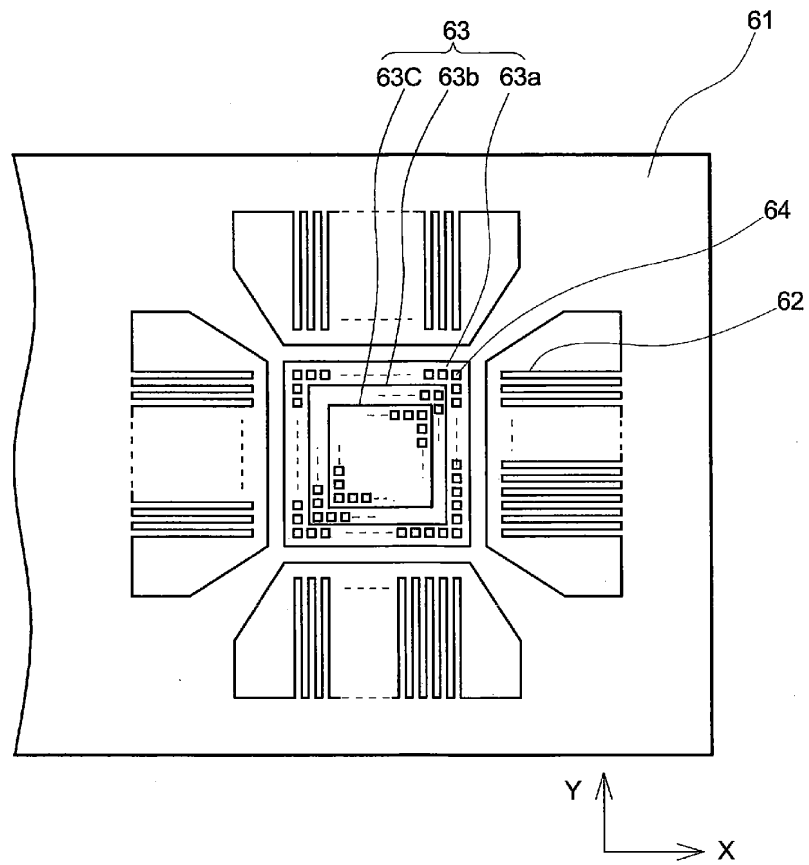
[図8]



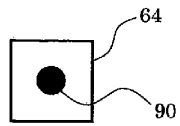
[図9]



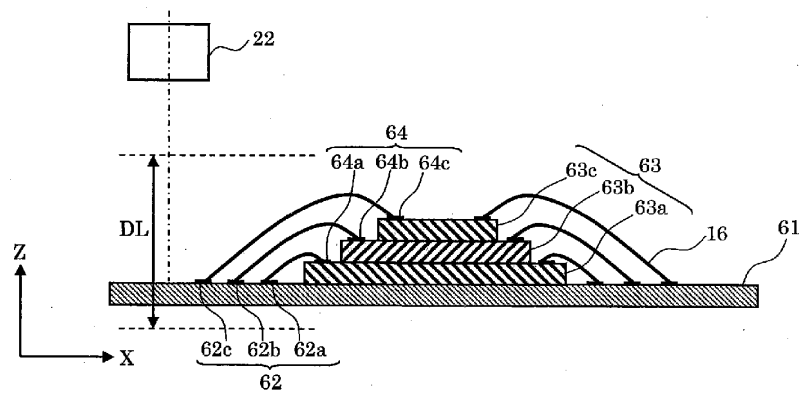
[図10]



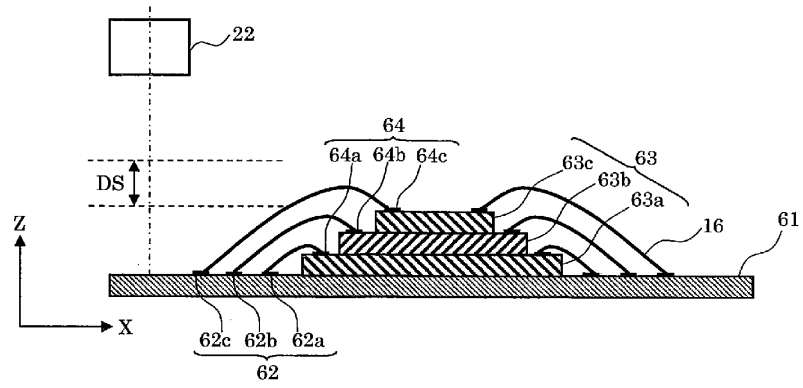
[図11]



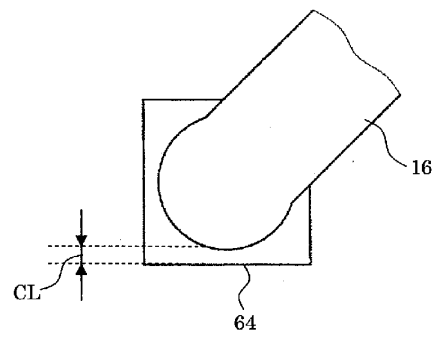
[図12]



[図13]



[図14]



[図15]

